MC10ELT28, MC100ELT28

5 V TTL to Differential PECL and Differential PECL to TTL Translator

ON Semiconductor®

www.onsemi.com

Description

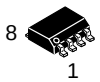
The MC10ELT/100ELT28 is a differential PECL to TTL translator and a TTL to differential PECL translator in a single package. Because PECL (Positive ECL) levels are used, only +5 V and ground are required. The small outline 8-lead package and the dual translation design of the ELT28 makes it ideal for applications which are sending and receiving signals across a backplane.

The 100 Series contains temperature compensation.

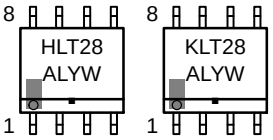
Features

- 3.5 ns Typical PECL to TTL Propagation Delay
- 1.2 ns Typical TTL to PECL Propagation Delay
- PNP TTL Inputs for Minimal Loading
- 24 mA TTL Outputs
- Flow Through Pinouts
- Operating Range V_{CC}= 4.75 V to 5.25 V with GND= 0 V
- Q_{TTL} Output Will Default High with Inputs Left Open or < 1.3 V
- Q_{ECL} Output Will Default High with Inputs Left Open
- Internal PECL Input Pulldown Resistors
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

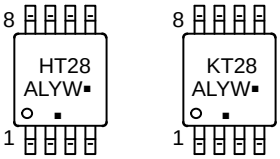
MARKING DIAGRAMS*



SOIC−8
D SUFFIX
CASE 751



TSSOP−8
DT SUFFIX
CASE 948R



H	= MC10	A	= Assembly Location
K	= MC100	L	= Wafer Lot
		Y	= Year
		W	= Work Week
		▪	= Pb−Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

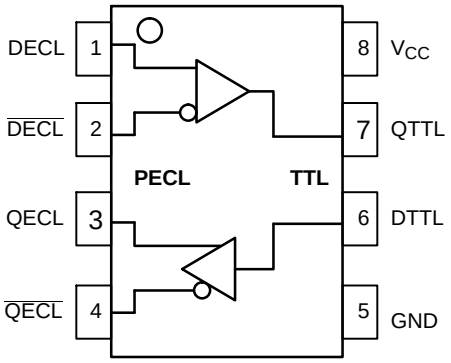


Figure 1. 8−Lead Pinout (Top View) **and Logic Diagram**

Table 1. PIN DESCRIPTION

Pin	Function
$Q\overline{TTL}$	TTL Outputs
$D\overline{TTL}$	TTL Data Inputs
QECL, $\overline{QECL}$	PECL Differential Outputs
DECL, $D\overline{ECL}$	PECL Differential Inputs
V_{CC}	Positive Supply
GND	Ground

Table 2. ATTRIBUTES

Characteristics		Value
ESD Protection	Human Body Model	> 2 kV
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)		Pb−Free Pkg
	SOIC−8 TSSOP−8	Level 1 Level 3
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in
Transistor Count		71 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test		

1. For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	Positive Power Supply	GND = 0 V		7	V
V_{IN}	Input Voltage	GND = 0 V	$V_I \leq V_{CC}$	0 to 6	V
I_{out}	PECL Output Current	Continuous Surge		50 100	mA mA
T_A	Operating Temperature Range			−40 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	SOIC−8 SOIC−8	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	SOIC−8	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	TSSOP−8 TSSOP−8	185 140	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	TSSOP−8	41 to 44 ± 5%	°C/W
T_{sol}	Wave Solder Pb−Free	<2 to 3 sec @ 260°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. 10ELT SERIES PECL DC CHARACTERISTICS V_{CC}= 5.0 V; GND= 0.0 V (Note 2)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OH}	Output HIGH Voltage (Note 3)	3920	4010	4110	4020	4105	4190	4090	4185	4280	mV
V_{OL}	Output LOW Voltage (Note 3)	3050	3200	3350	3050	3210	3370	3050	3227	3405	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	3770		4110	3870		4190	3940		4280	mV
V_{IL}	Input LOW Voltage (Single−Ended)	3050		3500	3050		3520	3050		3555	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 4)	2.2		5.0	2.2		5.0	2.2		5.0	V
I_{IH}	Input HIGH Current			255			175			175	μA
I_{IL}	Input LOW Current	0.5			0.5			0.3			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

2. Input and output parameters vary 1:1 with V_{CC}. V_{CC} can vary ± 0.25 V.
3. PECL outputs are terminated through a 50 Ω resistor to V_{CC} − 2 V.
4. V_{IHCMR} min varies 1:1 with GND, V_{IHCMR} max varies 1:1 with V_{CC}.

Table 5. 100ELT SERIES PECL DC CHARACTERISTICS V_{CC}= 5.0 V; GND= 0.0 V (Note 5)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{OH}	Output HIGH Voltage (Note 6)	3915	3995	4120	3975	4045	4120	3975	4050	4120	mV
V_{OL}	Output LOW Voltage (Note 6)	3170	3305	3445	3190	3295	3380	3190	3295	3380	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	3835		4120	3835		4120	3835		4120	mV
V_{IL}	Input LOW Voltage (Single−Ended)	3190		3525	3190		3525	3190		3525	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 7)	2.2		5.0	2.2		5.0	2.2		5.0	V
I_{IH}	Input HIGH Current			255			175			175	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

5. Input and output parameters vary 1:1 with V_{CC}. V_{CC} can vary ± 0.25 V.
6. PECL outputs are terminated through a 50 Ω resistor to V_{CC} − 2 V.
7. V_{IHCMR} min varies 1:1 with GND, V_{IHCMR} max varies 1:1 with V_{CC}.

Table 6. TTL OUTPUT DC CHARACTERISTICS V_{CC} = 4.75V to 5.25V; T_A = −40°C to 85°C

Symbol	Characteristic	Condition	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	I_{OH} = −3.0 mA	2.4			V
V_{OL}	Output LOW Voltage	I_{OL} = 24 mA			0.5	V
I_{CCH}	Power Supply Current			27	40	mA
I_{CCL}	Power Supply Current			29	42	mA
I_{OS}	Output Short Circuit Current		−150		−60	mA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

Table 7. TTL INPUT DC CHARACTERISTICS V_{CC} = 4.75 V to 5.25 V; T_A = −40°C to 85°C

Symbol	Characteristic	Condition	Min	Typ	Max	Unit
I_{IH}	Input HIGH Current	V_{IN} = 2.7 V			20	μA
I_{IHH}	Input HIGH Current	V_{IN} = 7.0 V			100	μA
I_{IL}	Input LOW Current	V_{IN} = 0.5 V			−0.6	mA
V_{IK}	Input Clamp Diode Voltage	I_{IN} = −18 mA			−1.2	V
V_{IH}	Input HIGH Voltage		2.0			V
V_{IL}	Input LOW Voltage				0.8	V

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

Table 8. AC CHARACTERISTICS V_{CC} = 4.75 V to 5.25 V (Note 8)

		−40°C			25°C			85°C			
Symbol	Characteristic	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Unit
f_{max}	Maximum Toggle Frequency		TBD			100			TBD		MHz
t_{PLH}	Propagation Delay @ 1.5 V DECL to QTTL DTTL to QECL	 2.0 0.6		 5.5 1.2	 2.0 0.9	 1.2	 5.5 1.5	 2.0 0.6		 5.5 1.35	ns
t_{PHL}	Propagation Delay @ 1.5 V DECL to QTTL DTTL to QECL	 2.0 0.4		 5.5 1.0	 2.0 0.5	 0.8	 5.5 1.1	 2.0 0.7		 5.5 1.3	ns
t_r, t_f	Rise/Fall Times (20% − 80%) QECL	0.15		1.5	0.15		1.5	0.15		1.5	ns
V_{PP}	PECL Input Swing (Note 9)	200		1000	200		1000	200		1000	mV
t_r/t_f	Output Rise Time (10% − 90%) Output Fall Time (10% − 90%)					1.6 1.1					ns ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

8. R_L = 500 Ω to GND and C_L = 20 pF to GND. Refer to Figure 2.
9. V_{PP}(min) is the minimum input swing for which AC parameters are guaranteed.

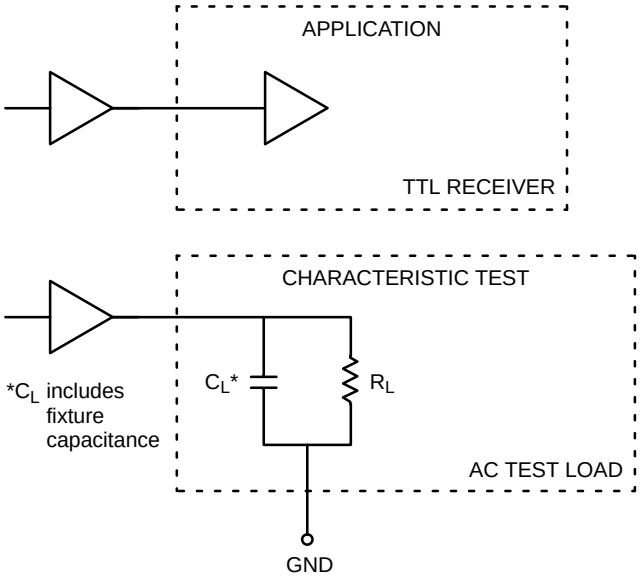


Figure 2. TTL Output Loading Used for Device Evaluation

ORDERING INFORMATION

Device	Package	Shipping†
MC10ELT28DG	SOIC−8 (Pb−Free)	98 Units / Rail
MC10ELT28DR2G	SOIC−8 (Pb−Free)	2500 / Tape & Reel
MC10ELT28DTG	TSSOP−8 (Pb−Free)	100 Units / Rail
MC10ELT28DTR2G	TSSOP−8 (Pb−Free)	2500 / Tape & Reel
MC100ELT28DG	SOIC−8 (Pb−Free)	98 Units / Rail
MC100ELT28DR2G	SOIC−8 (Pb−Free)	2500 / Tape & Reel
MC100ELT28DTG	TSSOP−8 (Pb−Free)	100 Units / Rail
MC100ELT28DTR2G	TSSOP−8 (Pb−Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D − ECL Clock Distribution Techniques

AN1406/D − Designing with PECL (ECL at +5.0 V)

AN1503/D − ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D − Metastability and the ECLinPS Family

AN1568/D − Interfacing Between LVDS and ECL

AN1672/D − The ECL Translator Guide

AND8001/D − Odd Number Counters Design

AND8002/D − Marking and Date Codes

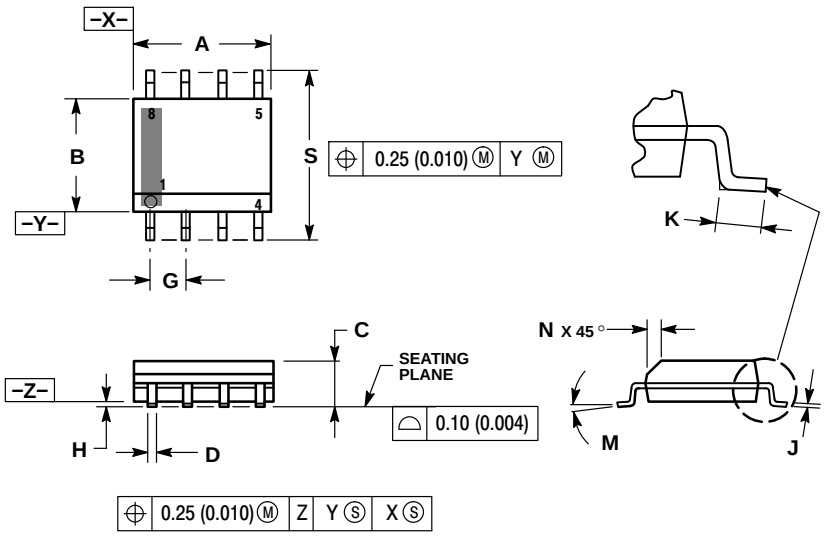
AND8020/D − Termination of ECL Logic Devices

AND8066/D − Interfacing with ECLinPS

AND8090/D − AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

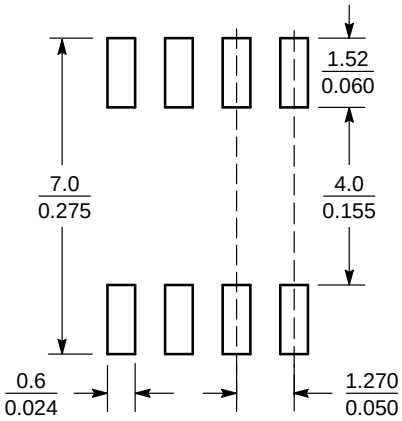
SOIC−8 NB
CASE 751−07
ISSUE AK



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDARD IS 751−07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

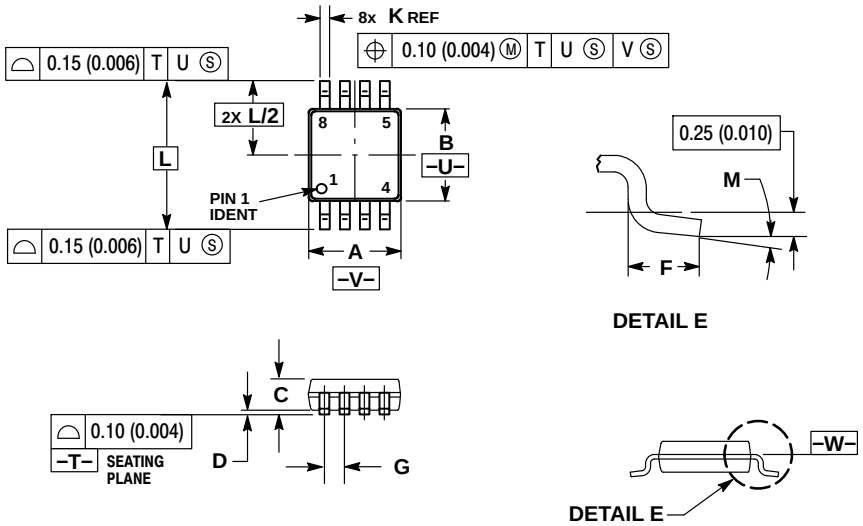


SCALE 6:1 (mm / inches)

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP−8
DT SUFFIX
CASE 948R−02
ISSUE A



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0 °	6 °	0 °	6 °

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PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
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